

ABSTRACT OF THE DISCLOSURE

A manufacturing process of package substrate is disclosed. The process is firstly disposing at least one passive component between a power pad and a ground pad of a package substrate, wherein two electrodes of the passive component connecting to the power pad and the ground pad, respectively; and then forming a metal layer on the electrodes of the passive component and exposed surfaces of all the conductive pads of the substrate. Therefore, during the subsequent wire bonding process, the two ends of the conductive wire can be respectively connected to a die pad of a die and an electrode of the passive component for improving yield and reliability of chip package fabrication.

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